



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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Features

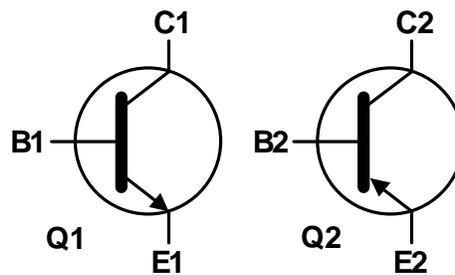
- Epitaxial Planar Die Construction
- Complementary Pair: 1 5551 Type NPN
1 5401 Type PNP
- Ideal for Medium Power Amplification and Switching
- Ultra-Small Surface Mount Package

Mechanical Data

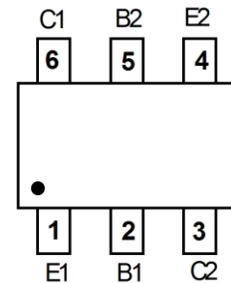
- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — Matte Tin Finish. Solderable per MIL-STD-202, Method 208 **e3**
- Weight: 0.006 grams (Approximate)



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings – NPN 5551 Section (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CB0}	180	V
Collector-Emitter Voltage	V _{CEO}	160	V
Emitter-Base Voltage	V _{EBO}	6	V
Continuous Collector Current	I _C	200	mA

Absolute Maximum Ratings – PNP 5401 Section (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CB0}	-160	V
Collector-Emitter Voltage	V _{CEO}	-150	V
Emitter-Base Voltage	V _{EBO}	-6	V
Continuous Collector Current	I _C	-200	mA

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	(Note 5)	200
		(Notes 6 & 7)	320
Thermal Resistance, Junction to Ambient	R _{θJA}	(Note 5)	625
		(Notes 6 & 7)	390
Thermal Resistance, Junction to Case	R _{θJC}	140	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	

- Notes:
5. For a device mounted on minimum recommended pad layout 1oz weight copper that is on a single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
 6. Same as Note 5, except the device is mounted on 25mm X 25mm 2oz copper.
 7. Maximum combined dissipation.
 8. Thermal resistance from junction to the top of package.

Electrical Characteristics – NPN 5551 Section (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

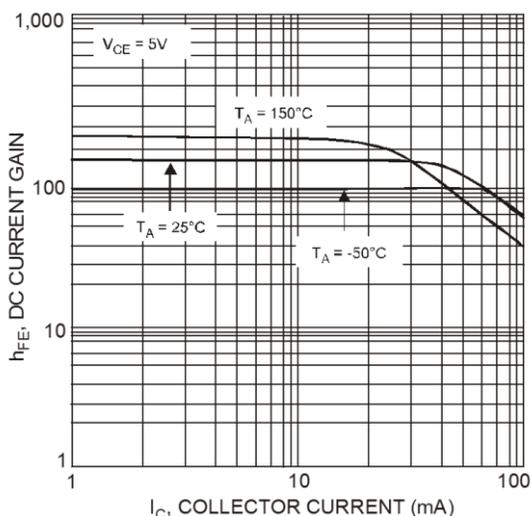
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV_{CBO}	180	—	—	V	$I_C = 100\mu\text{A}, I_E = 0$
Collector-Emitter Breakdown Voltage (Note 9)	BV_{CEO}	160	—	—	V	$I_C = 1\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	6	—	—	V	$I_E = 10\mu\text{A}, I_C = 0$
Collector-Base Cutoff Current	I_{CBO}	—	—	50	nA	$V_{CB} = 120\text{V}, I_E = 0$
		—	—	50	μA	$V_{CB} = 120\text{V}, I_E = 0, T_A = +100^\circ\text{C}$
Base-Emitter Cutoff Current	I_{EBO}	—	—	50	nA	$V_{EB} = 4\text{V}, I_C = 0$
ON CHARACTERISTICS (Note 9)						
DC Current Gain	h_{FE}	80	—	—	—	$I_C = 1.0\text{mA}, V_{CE} = 5.0\text{V}$
		80	—	250	—	$I_C = 10\text{mA}, V_{CE} = 5.0\text{V}$
		30	—	—	—	$I_C = 50\text{mA}, V_{CE} = 5.0\text{V}$
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	—	0.15	V	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$
		—	—	0.20	V	$I_C = 50\text{mA}, I_B = 5.0\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	—	—	1.0	V	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$
		—	—	1.0	V	$I_C = 50\text{mA}, I_B = 5.0\text{mA}$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C_{obo}	—	—	6.0	pF	$V_{CB} = 10\text{V}, f = 1.0\text{MHz}, I_E = 0$
Small Signal Current Gain	h_{fe}	50	—	250	—	$I_C = 1\text{mA}, V_{CE} = 10\text{V}, f = 1.0\text{MHz}$
Current Gain-Bandwidth Product	f_T	100	—	300	MHz	$I_C = 10\text{mA}, V_{CE} = 10\text{V}, f = 100\text{MHz}$
Noise Figure	NF	—	—	8.0	dB	$V_{CE} = 5.0\text{V}, I_C = 200\mu\text{A}, R_S = 1\text{k}\Omega, f = 1.0\text{kHz}$

Electrical Characteristics – PNP 5401 Section (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

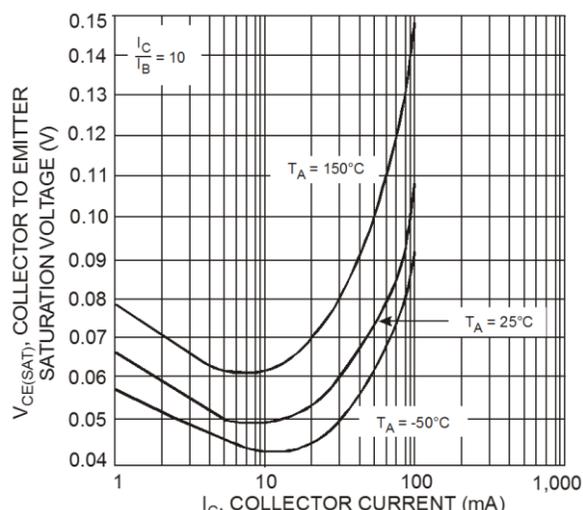
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV_{CBO}	-160	—	—	V	$I_C = -100\mu\text{A}, I_E = 0$
Collector-Emitter Breakdown Voltage (Note 9)	BV_{CEO}	-150	—	—	V	$I_C = -1\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV_{EBO}	-6	—	—	V	$I_E = -10\mu\text{A}, I_C = 0$
Collector-Base Cutoff Current	I_{CBO}	—	—	-50	nA	$V_{CB} = -120\text{V}, I_E = 0$
		—	—	-50	μA	$V_{CB} = -120\text{V}, I_E = 0, T_A = +100^\circ\text{C}$
Base-Emitter Cutoff Current	I_{EBO}	—	—	-50	nA	$V_{EB} = -4\text{V}, I_C = 0$
ON CHARACTERISTICS (Note 9)						
DC Current Gain	h_{FE}	50	—	—	—	$I_C = -1.0\text{mA}, V_{CE} = -5.0\text{V}$
		60	—	240	—	$I_C = -10\text{mA}, V_{CE} = -5.0\text{V}$
		50	—	—	—	$I_C = -50\text{mA}, V_{CE} = -5.0\text{V}$
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	—	-0.20	V	$I_C = -10\text{mA}, I_B = -1.0\text{mA}$
		—	—	-0.50	V	$I_C = -50\text{mA}, I_B = -5.0\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	—	—	-1.0	V	$I_C = -10\text{mA}, I_B = -1.0\text{mA}$
		—	—	-1.0	V	$I_C = -50\text{mA}, I_B = -5.0\text{mA}$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C_{obo}	—	—	6.0	pF	$V_{CB} = -10\text{V}, f = 1.0\text{MHz}, I_E = 0$
Small Signal Current Gain	h_{fe}	40	—	260	—	$I_C = -1\text{mA}, V_{CE} = -10\text{V}, f = 1.0\text{MHz}$
Current Gain-Bandwidth Product	f_T	100	—	300	MHz	$I_C = -10\text{mA}, V_{CE} = -10\text{V}, f = 100\text{MHz}$
Noise Figure	NF	—	—	8.0	dB	$V_{CE} = -5.0\text{V}, I_C = -200\mu\text{A}, R_S = 1\Omega, f = 1.0\text{kHz}$

 Note: 9. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

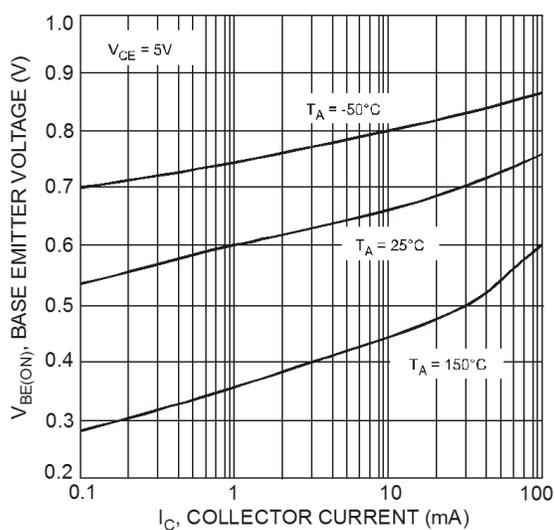
Typical Electrical Characteristics – NPN 5551 Section (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



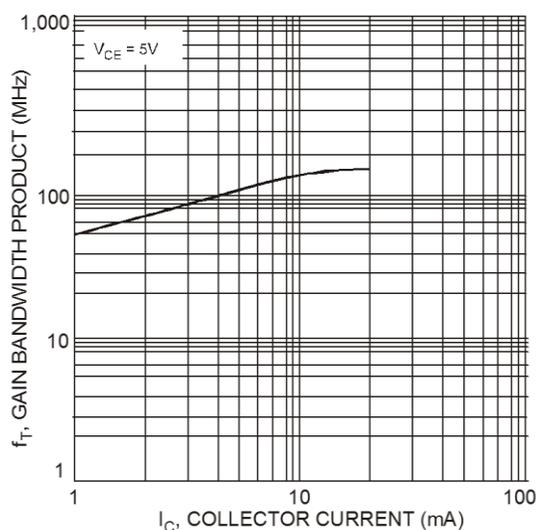
DC Current Gain vs. Collector Current



Collector Emitter Saturation Voltage vs. Collector Current

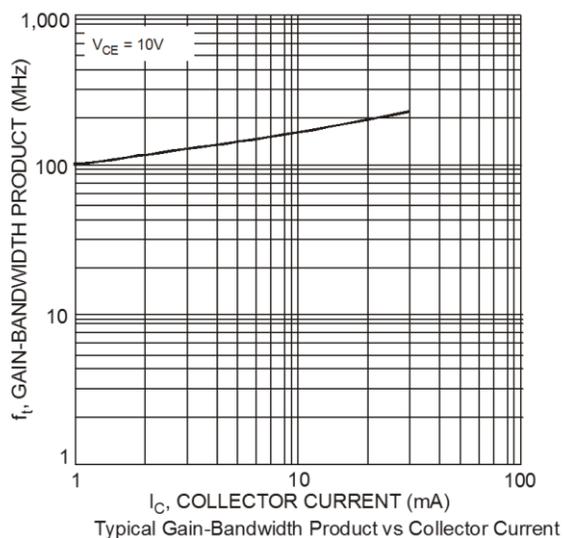
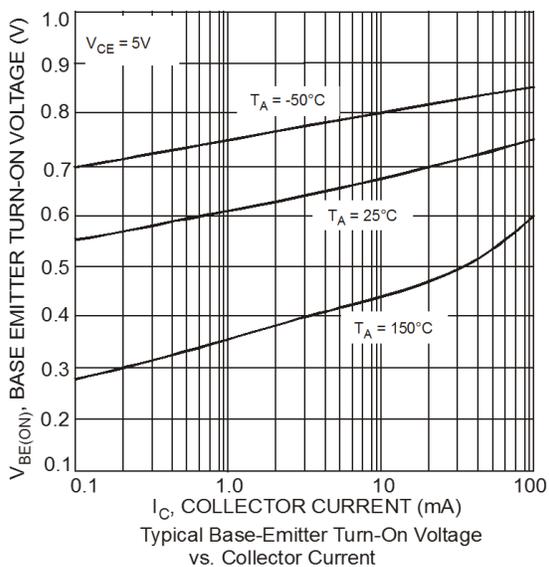
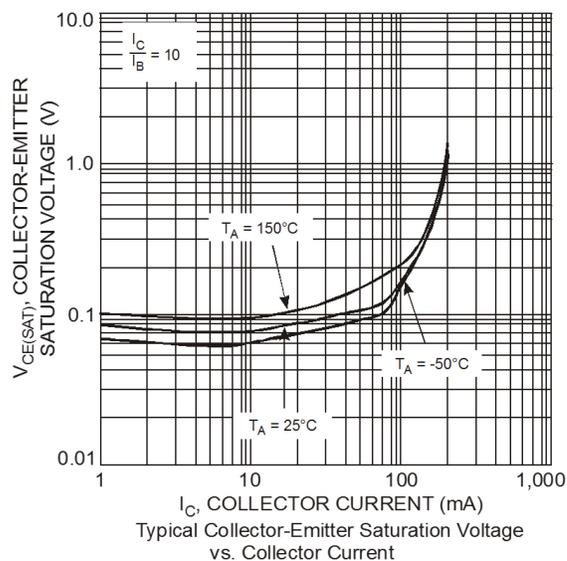
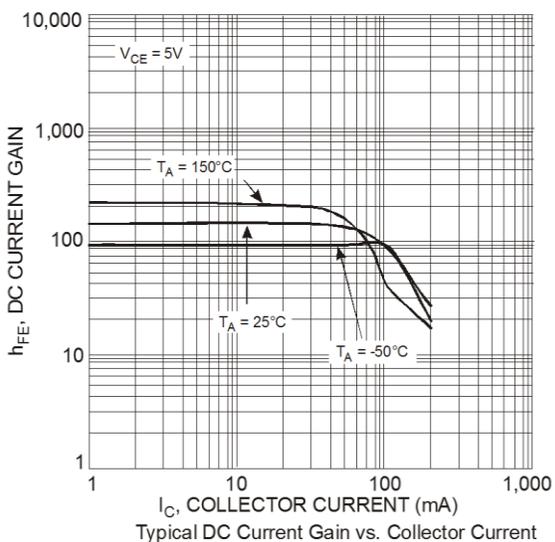


Base Emitter Voltage vs. Collector Current

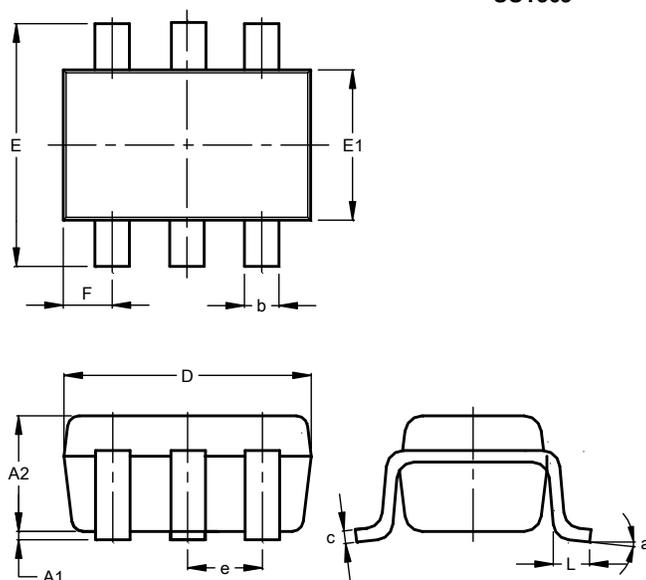


Gain Bandwidth Product vs. Collector Current

Typical Electrical Characteristics – PNP 5401 Section (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

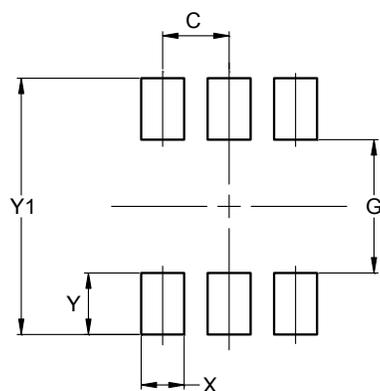


Package Outline Dimensions

SOT363


SOT363			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

SOT363


Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.